

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	AMS/20/12142	
<b>1.3 Title of PCN</b>	Introduction of new Resin, new Bonding wire and new DAP Plating on DPAK package in Subcontractor Nantong Fujitsu (TFME)	
<b>1.4 Product Category</b>	See product list	
<b>1.5 Issue date</b>	2020-08-11	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	NEMETH KRISZTINA
<b>2.1.2 Phone</b>	+49 89460062210
<b>2.1.3 Email</b>	krisztina.nemeth@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Marcello SAN BIAGIO
<b>2.1.2 Marketing Manager</b>	Salvatore DI VINCENZO
<b>2.1.3 Quality Manager</b>	Giuseppe LISI

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	Back end plant : Subcontractor Nantong Fujitsu (TFME China)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	- Bonding wire : Gold 1.5 mil - Molding compound : EME-500HA, Sumitomo - Lead frame : TIN Plating Pure Sn with plating Ag die pad	- Bonding wire : CU 1.5 mil - Molding Compound: EME-G700HF, Sumitomo - Lead frame = TIN Plating Pure Sn with Bare Copper die pad and lock hole
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	No impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	This change will contribute to ST's continuous service improvement and to improve the quality of the product, enhancing adhesion between lead frame surface & molding compound
<b>5.2 Customer Benefit</b>	QUALITY IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	New finished good codes
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2020-04-30
<b>7.2 Intended start of delivery</b>	2020-10-10
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	12142 12142_DPAK Cu wire.zip		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2020-08-11

**9. Attachments (additional documentations)**

12142 Public product.pdf  
12142 12142\_DPAK Cu wire.zip

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
L78M05CDT-TR	L78M05CDT-TR	
L78M12CDT-TR	L78M12CDT-TR	
LD1117DT33CTR	LD1117DT33CTR	
LD1117DT33TR	LD1117DT33TR	

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## Public Products List

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**PCN Title** : Introduction of new Resin, new Bonding wire and new DAP Plating on DPAK package in Subcontractor Nantong Fujitsu (TFME)

**PCN Reference** : AMS/20/12142

**Subject** : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

L78M05CDT-TR	LD1117DTTR	LD1117DT50TR
L78M12CDT-TR	LD1117DT33CTR	L78M05ABDT-TR
LD1117DT33TR	L78M05ACDT-TR	L78M09CDT-TR



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